This Sheet Has Been Replaced



Abstract:

Process and device for the shaping of connection pins of integrated circuits

The connection pins (14) of integrated circuits from which pins (14) lying in a common plane (21) project are bent by clamping the pins (14) close to their free ends and then, while maintaining the clamping, forcibly guiding the ends of the pins (14) along a curved path which lies in a plane running perpendicular to the common plane (21) and containing the respective pins (14).

(Figure 3)